

Package : HSIP

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1. Structure and materials

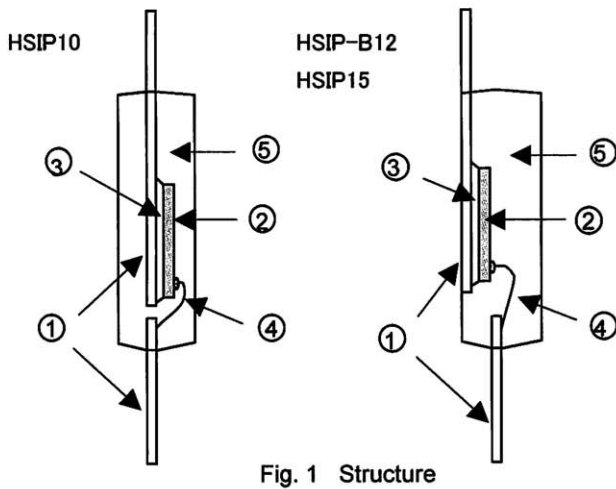


Fig. 1 Structure

No.	Item	Materials
①	Lead Frame	Cu-Alloy (External lead : Pb free solder plating)
②	Die	Silicon
③	Die Attach	Solder
④	Wire	Au
⑤	Molding	Epoxy Resin

2. Packing information

2.1. Packing specification

Container	Tube
Quantity	See the table on page 3/3

(all dimensions in mm)

2.2. Tube specification

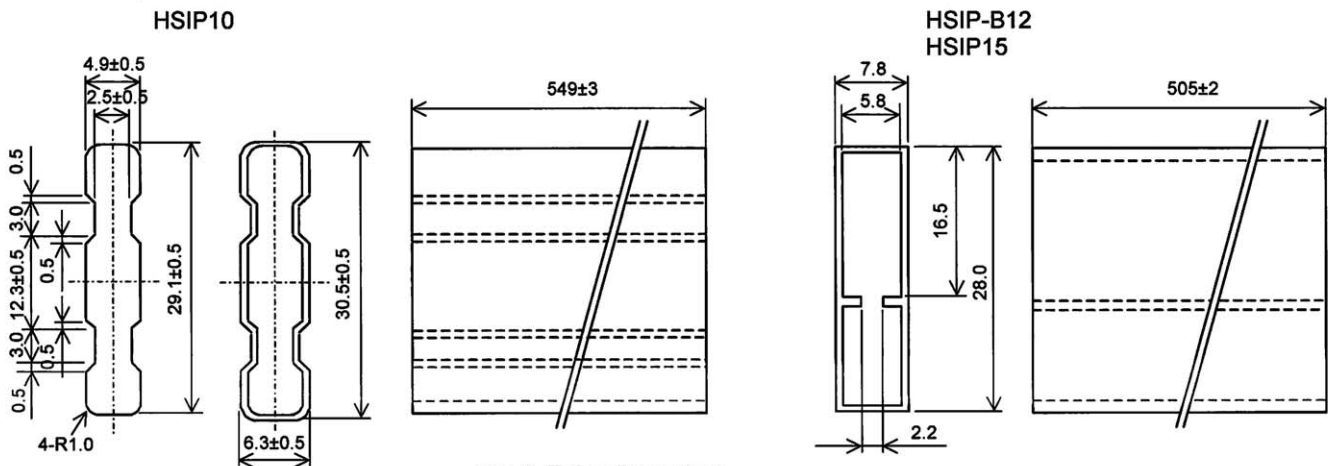


Fig. 2 Tube dimensions

2.3.Label for Box

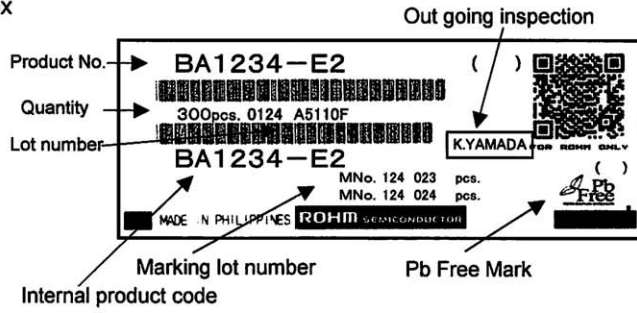


Fig. 3 Label example

2.4.Packing style

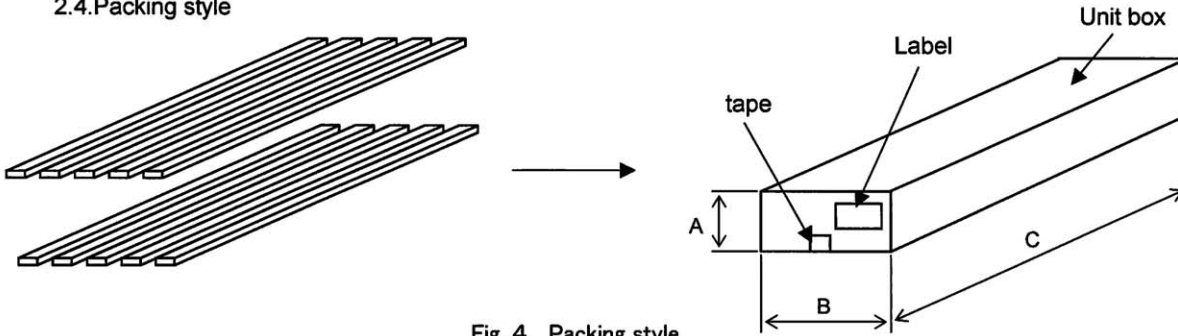
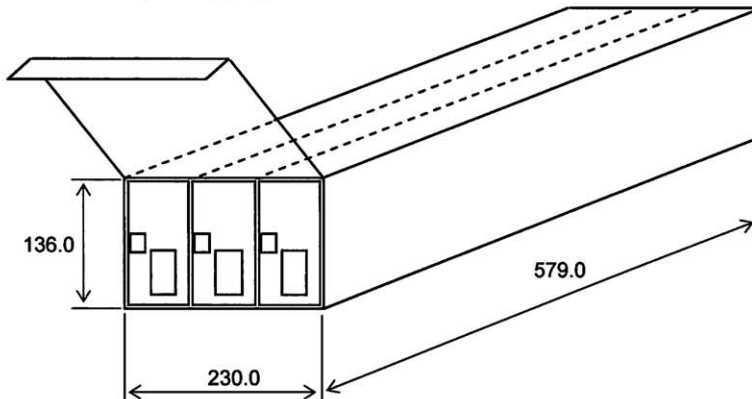


Fig. 4 Packing style

2.5.Shipping style

3 unit boxes or less per shipping box



(all dimensions in mm)

2.6.Packing materials

Item	Material
Tube	PVC
Stopper	PVC
Unit box	Cardboard
Shipping box	Cardboard

3.Storage conditions

3.1.Storage environment

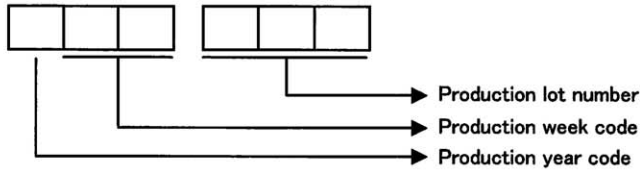
Recommended storage conditions are as follows :

- Temperature : 5 to 30°C
- Humidity : 40 to 70% RH

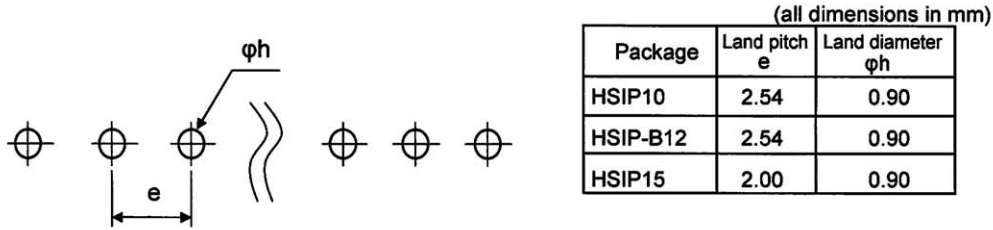
3.2. Storage period

- Specified storage period : 1 year

4. Marking lot number



5. Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



6. Soldering conditions

6. 1. Recommended temperature profile for reflow

Process	Conditions	
	Temperature	Time
Preheating	120°C to 150°C	60sec MAX
Soldering	260°C ± 3°C	12sec MAX

(Notice) Soldering time is provided for total soldering time in case of dual wave soldering.

6. 2. 1. Notes for wave soldering

- (1) Do not use other soldering methods with wave soldering.
- (2) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (3) Optimize soldering condition to prevent solder bridging.

6. 3. Recommended condition for solder iron

- Recommended condition for solder iron
- Solder iron temperature : 380°C or less
- Mounting time : 4sec or less

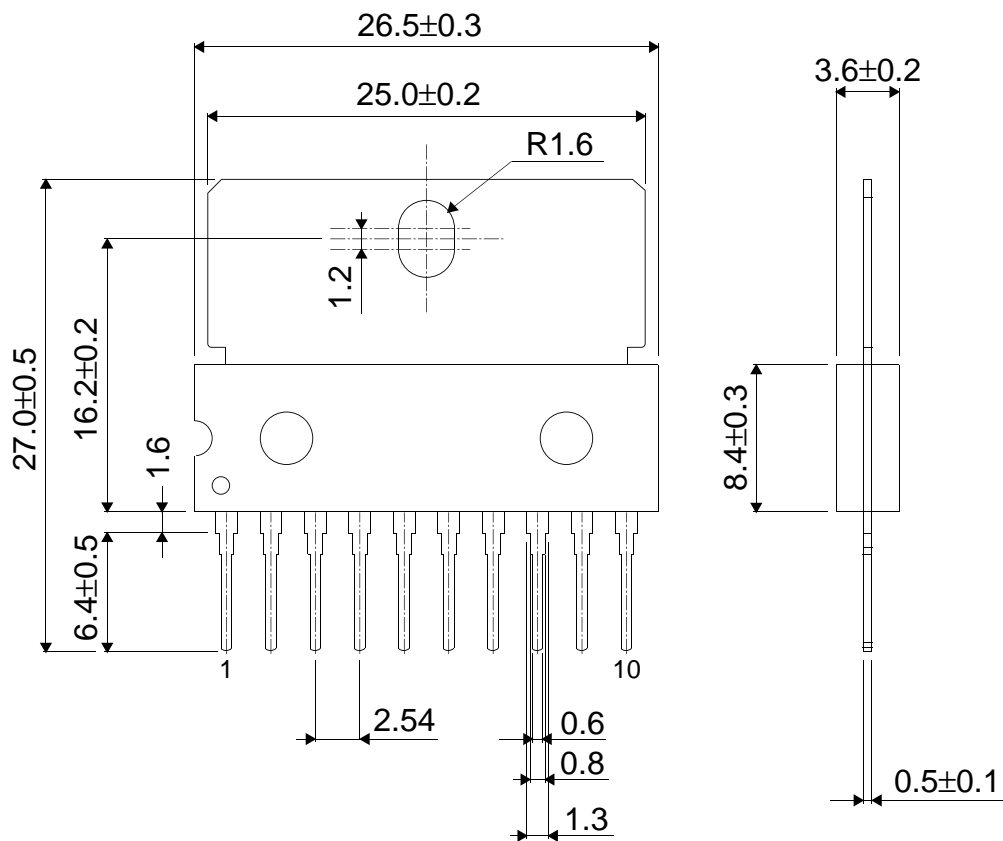
<Unit box dimensions >

<Dehydrated weight>

Package	Quantity (pcs)	Unit box dimensions (all dimensions in mm)			Dehydrated weight dimensions in g
		A	B	C	
HSIP10	500	60	130	555	2.93
HSIP-B12	300	70	130	510	3.09
HSIP15	300	70	130	510	3.31

Package Dimensions

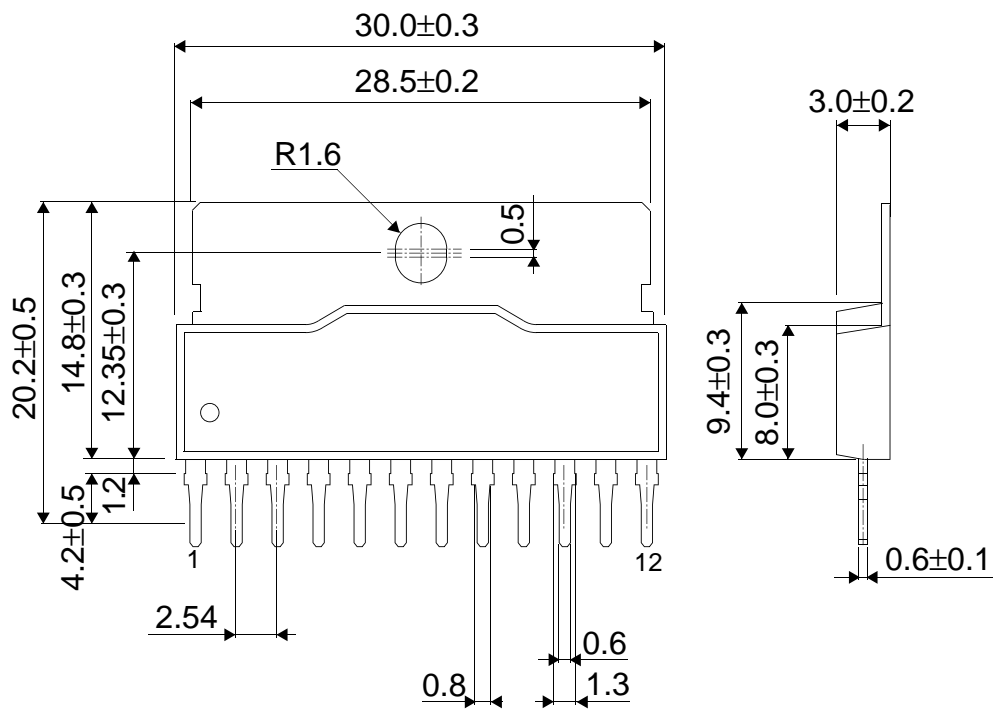
HSIP10



(Unit : mm)

Package Dimensions

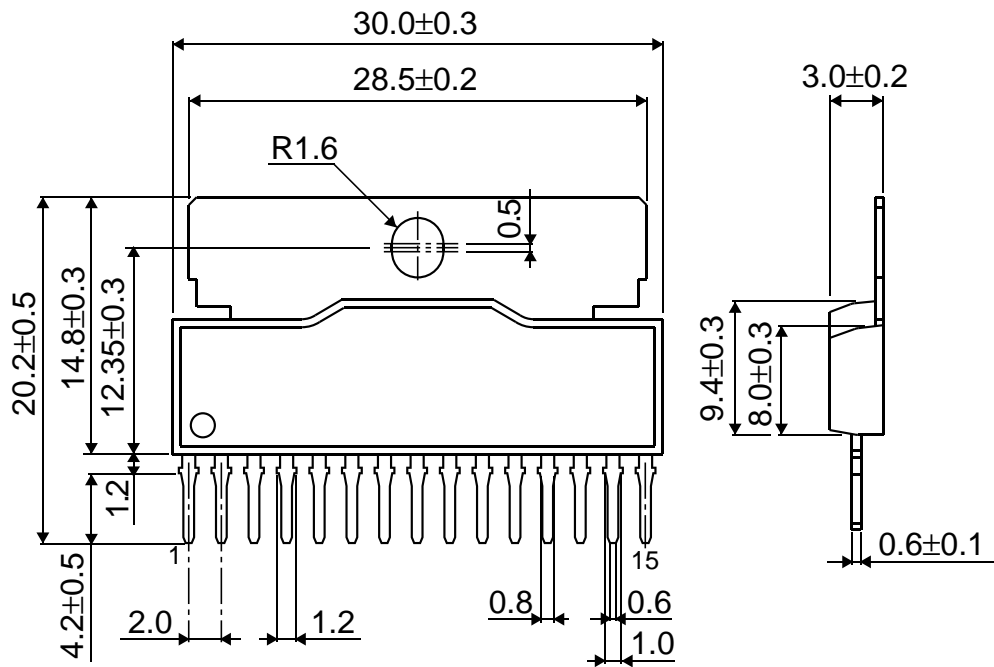
HSIP-B12



(Unit : mm)

Package Dimensions

HSIP15



(Unit : mm)

Notes

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